

Serial No 09/998,348

REMARKS

This amendment is supplementary to the amendment filed March 18, 2003. In telephone discussions with Examiner Patel on April 29, 2003 it was agreed that claim language provided in previous informal submissions by the undersigned was acceptable. It was also agreed that the non elected method claims 20-23 with amendments could be rejoined in the present application provided that claim 20 was amended to include limitations similar to those in the broadest ball grid array mounted circuit claims. The present amendment is believed to formalize the agreements reached on April 29..

Claim 1 has been amended to require that the solder connection cross section at the interposer be smaller at the interposer than at the electronic component and the PCB.

Claims 3 and 4 have been cancelled.

Minor revisions have been made to claim 12.

Claim 20 has been amended to include the limitation that the pads at the electronic component and the PCB be larger in size than the pads at the interposer and that the larger pads shape the solder connection to have a larger cross section at the electronic component and at the PCB than at the interposer.

The revised amendment instructions do not seem to make clear how to identify claims that were originally in the application as filed but were not elected following an election requirement and are later rejoined. In the listing of claims, claim 20 has been identified as currently amended and claims 21 and 22 have been identified as original.

Claim 23 has been cancelled.

Therefore, since the claims of the present invention have been shown to include limitations not taught or suggested by the references cited, the Examiner is requested to allow claims 1, 2, 5-22, and 24-27 and to pass this application to issue.

Respectfully submitted,

Date

5/1/03

Gregory A. Bruns

Gregory A. Bruns, Reg. No. 33,656
4612 Bruce Ave. So
Edina, MN 55424-1123
Phone 952/926-0862
E-Mail: gabruns@twincitizen.net